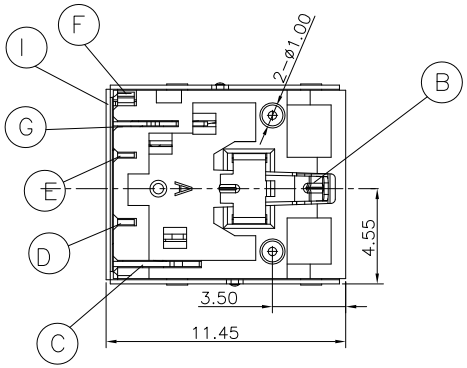
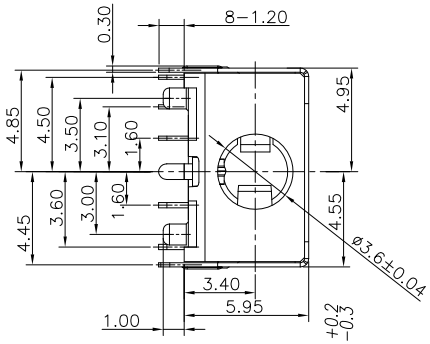
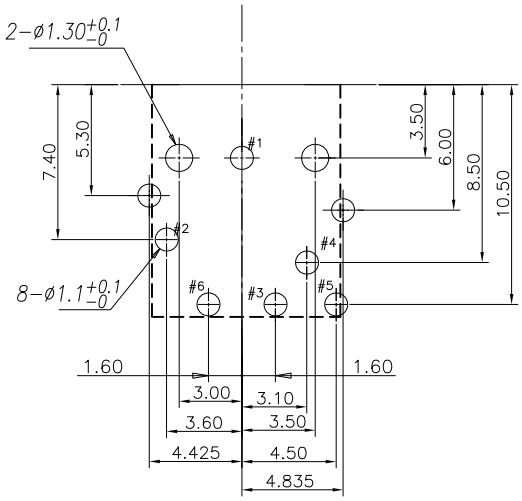
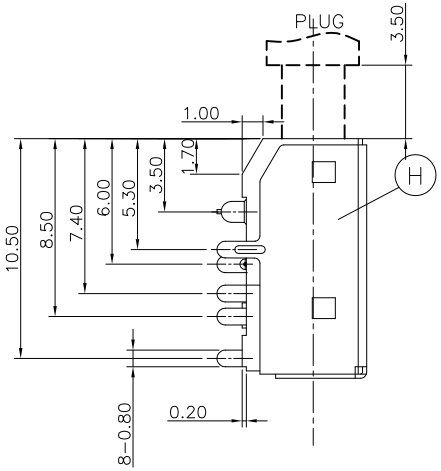
REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO.T120406-6A	Aaron	2012.05.02





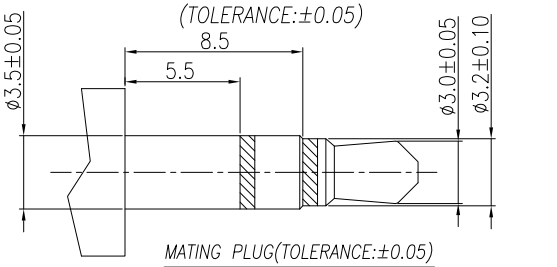


RECOMMENDED PCB LAYOUT (TOP VIEW)



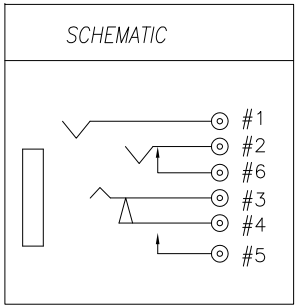
SPECIFICATIONS:

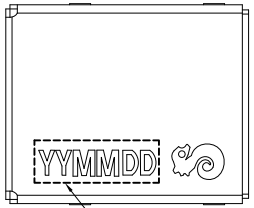
1. INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100MΩ MEASURED BY 500 VDC MEGGER.
2. CONTACT RESISTANCE: 30mΩ MAX.
3. INSULATION VOLTAGE WITHSTAND; 500V AC FOR ONE MINUTE.
4. UNLESS OTHERWISE SPECIFIED. TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
5. LIFE TEST: 5,000 CYCLES MIN. (NON-LOAD)
6. INSERTION FORCE:0.4 - 3Kg.
7. WITHDRAWAL FORCE:0.3 - 2Kg.
8. AFTER LIFE TEST, CONTACT RESISTANCE: 50mΩ MAX.
9. AFTER HUMIDITY TEST, INSULATION RESISTANCE:50MΩ MIN.
10. MARKING: MARK" " ON TOP OF CONNECTOR.
11. PACKAGING : TAPE & REEL.
12. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
13. HALOGEN FREE PRODUCT IDENTIFICATION MARK ON PRODUCT:
14. HALOGEN FREE PRODUCT IDENTIFICATION LOGO ON PACKAGING:
15. FOR LEAD-FREE PROCESS.



MATING PLUG(TOLERANCE:±0.05)

ø3.5 3-POLE STANDARD PLUG





DATE CODE.

NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
I	MYLAR	1	KAPTON	YELLOW
H	SHIELDING	1	BRASS 0.2t	Ni 60u" Min
G	TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	120u" Sn ON SOLDER GOLD FLASH ON CONTACT AREA ALL OVER 50u" Ni.
F	BREAK TERMINAL	1	PHOSPHOR BRONZE 0.2t	
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	
D	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD FLASH ON CONTACT AREA ALL OVER 50u" Ni.
C	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag20u"Min,ALL OVER 50u" Ni .
B	EARTH	1	COPPER ALLOY 0.2t	GOLD FLASH ,Ni 60 u" Min
A	BODY	1	HIGH TEMP.THERMOPLASTIC UL 94V-0	BLACK

UNLESS OTHERWISE SPECIFED TOLERANCES

DECIMALS: X :±0.5 X.X :±0.3 X.XX :±0.2

ANGLES: X :±2° X.X :±1°

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

TITLE	3.5ø PHONE JACK			
DWN	Aaron	PART NO.2SJ3018-006311F		
CHKD	Bruce	SCALE:4:1	UNIT: mm	
APVD	Lussen	SIZE: A3	SHEET:1 OF 1	REV:A

CUSTOMER COPY

文件編號 RD-06-043-A